

**PATENT APPLICATION**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Hiroyuki KUMAKURA

Group Art Unit: 2841

Application No.: Rule 53(b) Divisional Application of  
U.S. Application No. 09/603,840

Examiner: I. Patel

Filed: November 26, 2001

Docket No.: 106589.01

For: METHOD FOR CONNECTING ELECTRICAL COMPONENTS (AS AMENDED)

**PRELIMINARY AMENDMENT**

Director of the U.S. Patent and Trademark Office  
Washington, D. C. 20231

Sir:

Prior to initial examination, please amend the above-identified application as follows:

**IN THE TITLE:**

Please replace the title as follows:

METHOD FOR CONNECTING ELECTRICAL COMPONENTS

**IN THE CLAIMS:**

Please replace claim 2 as follows:

2. (Amended) A connection method, comprising:

electrically connecting first electrodes on a first substrate and second electrodes on a second substrate with an interposed anisotropic electroconductive adhesive layer, wherein the thickness of the electroconductive adhesive layer prior to connection is given by:

$$0.5 \times \{(A^1C^1 + A^2C^2) / (B+C)\} \leq X \leq 2 \times \{(A^1C^1 + A^2C^2) / (B+C)\}$$

where:

$A^1$  is the height of each first electrode,  $B^1$  is the width of each first electrode,  $C^1$  is the width of the interelectrode space for the first electrodes,  $A^2$  is the height of each second electrode,  $B^2$  is the width of each second electrode,  $C^2$  is the width of the interelectrode space for the second electrodes (provided that  $B + C = B^1 + C^1 = B^2 + C^2$ ), and  $X$  is the thickness of the electroconductive adhesive layer prior to connection.

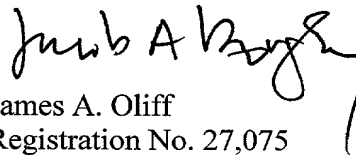
REMARKS

Claim 2 is pending. By this Preliminary Amendment, the Title and claim 2 are amended. No new matter is added. The amendments are not believed to narrow the scope of claim 2.

The attached Appendix includes a marked-up copy of the rewritten claim (37 C.F.R. 1.121(c)(1)(ii)).

Prompt and favorable examination on the merits is respectfully requested.

Respectfully submitted,

  
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## APPENDIX

## Changes to Title:

The following is a marked-up version of the amended title:

~~CONNECTION STRUCTURE~~ METHOD FOR CONNECTING ELECTRICAL  
COMPONENTS

## Changes to Claims:

The following is a marked-up version of the amended claim:

2. (Amended) A connection method, comprising:

\_\_\_\_\_ ~~for~~ electrically connecting first electrodes on a first substrate and second electrodes on a second substrate with an interposed anisotropic electroconductive adhesive layer, wherein ~~said connection method satisfies Eq. 1 below~~ the thickness of the electroconductive adhesive layer prior to connection is given by:

$$0.5 \times \{(A^1 C^1 + A^2 C^2) / (B + C)\} \leq X \leq 2 \times \{(A^1 C^1 + A^2 C^2) / (B + C)\} \text{ ——— (1)}$$

\_\_\_\_\_ where:

\_\_\_\_\_ -  $A^1$  is the height of each first electrode,  $B^1$  is the electrode width thereof,  $C^1$  is the width of the interelectrode space,  $A^2$  is the height of each second electrode,  $B^2$  is the electrode width thereof,  $C^2$  is the of the interelectrode space (provided that  $B + C = B^1 + C^1 = B^2 + C^2$ ), and  $X$  is the thickness of the electroconductive adhesive layer prior to connection.